

DDR4 MEMORY MODULE SOCKETS

OVERVIEW

Vertical DDR4 DIMM sockets from FCI provide 288 contacts on 0.85mm pitch and are designed to accept DDR4 memory modules that conform to JEDEC MO-309. The sockets facilitate convenient memory expansion in servers, workstations, desktop PCs, and embedded applications in communications and industrial equipment. A new special housing is also available allowing trenches along the sockets to be fitted with passive components.

The low-resistance contacts also support the use of RDIMM (registered DIMM), which helps to further reduce power consumption in datacenter hardware such as servers, storage and networking equipment. The low 2.4mm module seating plane and slim ejector designs reduce the overall profile of the connector and installed module to help optimize airflow.

Surface-mount (SMT), plated-through-hole (PTH) solder, and press-fit (PF) connector termination options are offered.



FEATURES

- SMT termination with trenches at board bottom
- Low insertion-force
- Multifarious tail length
- Slim latch design
- RoHS-Compliant, low halogen and lead-free process-compatible

BENEFITS

- Allows space to mount small passive components on the board bottom to maximize PCB space utilization
- Easy to insert and extract the module
- Support 1.6mm or 2.4mm thick motherboards
- Optimizes airflow
- Meets environment requirements



TECHNICAL INFORMATION

MATERIALS

- Contact : Copper Alloy
- Contact Finish:
 - Contact Area: 15µin. , 30µin. Gold or GXT™ over Nickel
 - Termination Area: Tin over nickel
- Forklock: Copper Alloy
- Housing: High-Temperature thermoplastic, UL94V-0
- Ejector: High performance thermoplastic, UL94V-0

ELECTRICAL PERFORMANCE

- Contact Resistance: ≤ 10mΩ initial, ≤ 10mΩ increase-after environmental test
- Current Rating: 0.75A/contact (De-rated) with ≤ 30 °C temperature rise above ambient

MECHANICAL PERFORMANCE

- Durability: 25 cycles

SPECIFICATIONS

- FCI
 - Product Specification: GS-12-1092
 - Packaging Specification: GS-14-2267
 - Application Specification: GS-20-0353
- JEDEC
 - Module Outline: MO-309
 - Socket Outlines:
 - PTH solder: SO-016
 - Surface-mount: SO-017
 - Press-fit: SO-019

PACKAGING

- Tray

APPROVALS & CERTIFICATIONS

- UL E66906

TARGET MARKETS/APPLICATIONS

- Data
 - Servers
 - Storage Systems
 - Supercomputers
- Workstations
- Desktop PCs
- Communications
 - Switches
 - Routers
 - Wireless Infrastructure
- Industrial
 - Embedded Systems

PART NUMBERS

Type	Color Option	Part Number
Surface Mount (SMT) termination with forklocks or solder tabs	Housing: Black and Nature Ejectors: Black and Nature	10124677
Plated-Through-Hole (PTH) Solder-termination with forklocks	Housing: Black, Nature and Blue Additional Colors available Ejectors: Black, Nature and Blue	10124632 10129040 10130419
Press fit (PF) termination with molded post	Housing: Black, Nature and Blue Additional Colors available Ejectors: Black, Nature and Blue	10124806

BWBDDR4MMS1014EA4

Disclaimer

Please note that the above information is subject to change without notice.